Speedline Asia E-News
Vol: 14
Date: 27 May 2010

Speedline receives multiple awards for.....

Reflow Soldering technology

Speedline's Electrovert OmniMax™ Reflow Soldering System was honoured with 3 awards this April. The first one is the New Product Introduction Award given by Circuit Assembly magazine at ceremonies held at the IPC APEX trade event in Las Vegas on April 6. The second and third award was presented by *SMT* China Magazine to Speedline Technologies during ceremonies held on April 20th at the Nepcon China trade event in Shanghai. These was the prestigious Vision Awards. The awards presented were Best Product in the Reflow Soldering Category and the Innovation Award.

Winners for both event were honored for their innovativeness, cost-effectiveness, speed/ throughput improvements, quality contribution, technology advancement, ease-of-use, maintainability and repairability.

John Neiderman, Application Sales Engineer for Electrovert receiving the award for Speedline at the SMT China Vision award ceremony in Shanghai, China.

Printing technology

Speedline's MPM Momentum Dual Lane technology received the *SMT* Vision Awards for Best Product in the Printing Equipment category and the MPM Rapid View Inspection system won in the Inspection category in award ceremony at IPC APEX, Las Vegas.

RapidView Inspection was also awarded the EM Asia Innovation Award for Best Product in the Stencil and Screen Printing Systems/ Equipment category at the award ceremony in Nepcon China, Shanghai 2010.

Top performiing companies were recognised for achieving the highest standards in manufacturing-related products, materials and equipment.

Adam Sim, Product Business Manager, MPM and SM Fong, Manager, Marketing Communications receiving the award for Speedline at the EM Asia award ceremony.

OmniMax™ Reflow Soldering System

Through innovation combined with over 25 years of reflow technology expertise, Electrovert

introduces the OmniMax reflow soldering system. As high reliability SMT PCB's become more complex and process windows continue to decrease, manufacturers are looking for technologies that improve product reliability, reduce costs associated with rework or scrap, reduce operating costs, and still provide the levels of throughput from an in-line reflow oven.

Issues with a typical in-line reflow oven:

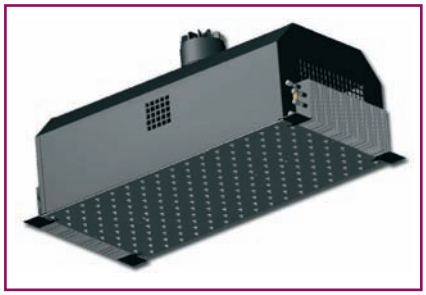
- Process drift of critical parameters over time
- Thermal inconsistency across the entire PCB throughout the reflow process
- Hidden costs associated with end-product reliability
- Difficult and expensive to maintain

The OmniMax solution:

- Electrovert's innovative approach to thermal transfer delivers super efficient heat transfer throughout the entire process
- Efficient control of convection dynamics provides well-defined transitions between zones
- Introduction of new technologies provides an industry-first 'dripless' cooling
- Innovations in exhaust flow and management significantly reduce maintenance in the cooling zone
- Designs that provide control of key performance attributes result in lower N2 consumption levels

OmniMax benefits:

- The OmniMax thermal performance has reproduced profiles formerly only achievable by vapor phase processes which ultimately provides higher product reliability.
- Lower N2 consumption results in cost savings.
- Maintenance intervals can be extended and maintenance is performed in less time.
- Consistent thermal performance in a demanding production environment is obtained throughout the span of the product life cycle .



IsoThermal Chamber Technology (ICT)

Speedline Electrovert continues to be the industry leader of innovation and provider of process solutions worldwide.

For more information on the OmniMax, contact your neareast Speedline Technologies contacts or visit *www.speedlinetech.com*.

Next issue :

⇒ Electrovert's IsoThermal Chamber Technology (ICT)

⇒ Aspect ratio or Area ratio for Optimal Paste transfer - Which formula to use?

Service Tip :

Stencil Variables

Stencil variables must be under control to maximize solder paste transfer and deposition accuracy during the stencil printing process.

Aperture width relative to pad width - impacts print quality, paste transfer deposition volume.

Wall smoothness - impacts solder paste release, solder paste transfer efficiency, deposition volume.

Aperture and stencil thickness tolerance - impacts deposition thickness and volume causing bridging and insufficient.

Trapezoidal apertures - impact deposition volume, paste transfer efficiency.

Stretch during stencil assembly - impacts deposition accuracy.

Foil distance outside image area - impacts print quality.

Stencil thickness - determines deposition height, print quality, bridging and insufficient.

Fiducial location and fill - impacts board and stencil alignment, deposit accuracy.

Gasketing - impacts print quality & bridging.

ABOUT SPEEDLINE TECHNOLOGIES

Speedline Technologies is the global leader in process knowledge and expertise for the PCB assembly and semiconductor industries. Based in Franklin, Massachusetts, U.S.A., the company markets five best-in-class brands — Accel microelectronics cleaning equipment; Camalot dispensing systems; Electrovert wave soldering, reflow soldering, and cleaning equipment; MPM stencil and screen printing systems; and PROTECT global services, support, and training solutions. For more information, visit us at www.speedlinetech.com.

Speedline technologies

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